

Title (en)

Method for manufacturing backing pad and apparatus used therefor

Title (de)

Verfahren und Vorrichtung zum Herstellen von Stützunterlagen

Title (fr)

Procédé et dispositif pour la fabrication de patins d'appui

Publication

EP 0798078 A2 19971001 (EN)

Application

EP 97302066 A 19970326

Priority

JP 10437196 A 19960328

Abstract (en)

A method and an apparatus for manufacturing a grooved backing pad suitable for use in polishing of semiconductor wafer based on the waxless method. The backing pad manufacturing apparatus contains a load/unload conveyer 11 and a groove forming unit 21 above a chuck table 4. The main body 22 of the groove forming unit comprises an aluminium-made hollow axis 26 and a plurality of aluminium-made round flanges arrayed thereon. These round flanges having an almost equal diameter are aligned concentrically with the hollow axis and fixed thereon along its longitudinal direction. In a fabrication process of the grooved backing pad, a work fixed on a sheeted elastic member is vacuum-chucked on the chuck table using the load/unload conveyer, steam is supplied through the hollow axis 26 to heat the round flanges 27 to the softening point of the sheeted elastic member or above, and the round flanges are roll-contacted to the surface of the sheeted elastic member under pressure by traveling the main body 22 of the groove forming unit along the surface of the member. <IMAGE>

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Cited by

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